

07/08/03
15868 U.S. PTO



27649
PATENT TRADEMARK OFFICE

Attorney Docket No. 1047

PATENT

15868 U.S. PTO
10/614351
07/08/03

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The patent application of

Inventor(s): AMAGAI ET AL

For: LEAD-FREE SOLDER ALLOY

is attached for filing.

- [x] This application is being filed without a declaration or fee.
- [x] This application claims the priority of:
Japanese Patent Application No. 2002-199666 filed on July 9, 2002, and
Japanese Patent Application No. 2002-217925 filed on July 26, 2002

Respectfully submitted,

Michael Tobias
Registration Number 32,948

#40
1717 K Street, N.W., Suite 613
Washington, D.C. 20036
Telephone: (301) 587-6541
Facsimile: (301) 587-6623
Date: July 8, 2003